2014 IEEE International Conference on Signal and Power Integrity (SIPI-2014)

an embedded conference within the

2014 IEEE International Symposium on Electromagnetic Compatibility

Dates: 4 - 8 August 2014

Location: Raleigh Convention Center, Raleigh, NC, USA

2014 IEEE International Conference on Signal and Power Integrity (SIPI 2014) will be held as an embedded conference within the 2014 IEEE International Symposium on Electromagnetic Compatibility the week of August 4 - 8, 2014. Registered attendees will have access to the entire EMC Symposium program, in addition to the programs of SIPI 2014, without additional fees. As high-speed designs continue to evolve, signal/power integrity and other EMC problems are becoming more tightly related. This conference provides a unique opportunity for attendees to exchange ideas and share experiences relevant to today's high-speed designs.

Join your colleagues and experts/innovators in Raleigh, NC for a full week of technical presentations on advances and research in EMC, SI, PI and other related fields. Conference proceedings will be submitted for posting to IEEE Xplore. In addition, authors of accepted papers will be invited to submit an extended version of their symposium paper for possible publication in a special issue of the IEEE Transactions on Electromagnetic Compatibility. Proposals for special sessions, workshops, tutorials, and experiments are also encouraged.

Topics of interest in the signal and power integrity conference include, but are not limited to, the following technical areas. We welcome input and recommendations for new topics in the relevant fields as well.

- Signal/power integrity for chip/package/board/connector/cable design
- Signal integrity and power integrity co-simulation
- Design, analysis, simulation, modeling and measurement techniques
- Simulation and measurement correlation
- High-speed interconnect design and optimization (component and/or system level)
- PDN (power delivery network) design and optimization
- Device modeling and characterization
- Jitter/Noise/Crosstalk and BER analysis
- System-level SI/PI/EMI co-design
- Test and measurement

Paper submission:

- Deadline: January 20, 2014

Check website for more details about conference registration, paper submission information, travel and lodging.

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www.emc2014.org/SIPI2014